



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		* : Required Field


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	17-02-2022
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F217IGH6 STM8L101G3U6TR	E0MR*411XXXV	A	9991	17-02-2022
	Amount	UoM	Unit type	ST ECOPACK Grade
	111.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SN96.5 AG3.5%	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	10x10	176	bulk solder	
Comment	Package : A0E7 UFBGA 10X10X0.6 176+25 P0.65 8249558			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH - 8th July 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	EOMR*411XXXV				5999999.0	1000008.8
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die, or dies	M-011 Other inorganic materials	2.573	mg	supplier	die	Silicon (Si)	7440-21-3		2.073	mg	805674	18676
				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	9328	216
				supplier	metallization	Copper (Cu)	7440-50-8		0.211	mg	82005	1901
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	389	9
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.068	mg	26428	613
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	1166	27
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	777	18
				supplier	Passivation	Silicon Nitride	12033-89-5		0.054	mg	20987	486
				supplier	Passivation	Silicon Oxide	7631-86-9		0.137	mg	53245	1234
				Substrate A26822-0	M-011 Other inorganic materials	40.180	mg	supplier	BT-substrate	Thermosetting resin (including filler)	Proprietary	
	BT-substrate	Glass cloth	65997-17-3						10.849	mg	270000	97735
	BT-substrate	Copper foil	7440-50-8						9.938	mg	247340	89533
	Solder mask	3-methoxy-3-methylbutyl acetate	103429-90-9						7.294	mg	181530	65711
	Solder mask	Dipropylene glycol monomethyl ether	34590-94-8						1.866	mg	46450	16814
	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.462	mg	11500	4163
	Solder mask	Morpholine derivative	Trade Secret						0.482	mg	12000	4344
	Solder mask	Napthalene (Carc. Cat. 3,R40)	91-20-3						0.047	mg	1170	424
	Solder mask	Barium Sulfate	7727-43-7						4.822	mg	120000	43438
Glue ABLESTICK ATB-125	M-011 Other inorganic materials	2.520	mg					supplier	Glue or tape	Butadiene, acrylonitrile polymer, carboxy-tern	68610-41-3	
					Glue or tape	Formaldehyde, polymer with (chloromethyl)op	37382-79-9		0.607	mg	241000	5471
					Glue or tape	Dapsone	80-08-0		0.060	mg	24000	545
					Glue or tape	Siloxanes and Silicones, di-Me, reaction produ	67762-90-7		0.063	mg	25000	568
					Glue or tape	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	Proprietary		0.050	mg	20000	454
					Glue or tape	1,3-Butadiene, acrylonitrile copolymer, 3-carb	68891-46-3		0.050	mg	20000	454
Bonding wire (Au 0.8mils)	Precious metals	1.405	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		1.405	mg	1000000	12658
Encapsulation (G1250AAS ULA)	M-011 Other inorganic materials	59.433	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		53.906	mg	907000	485637
					Molding Compound	Epoxy resin	Trade Secret		2.972	mg	50000	26772
					Molding Compound	Phenol resin	Trade Secret		2.377	mg	40000	21417
					Molding Compound	Carbon Black	1333-86-4		0.178	mg	3000	1606
					Solder	Tin (Sn)	7440-31-5		4.719	mg	965000	42512
Solder balls (200 DIAM SN96.5 AG3.5)	Solder	4.890	mg	supplier	Solder	Silver (Ag)	7440-22-4		0.171	mg	35000	1542